

IN THE CLAIMS:

Please amend the claims as follows:

1-49. (Canceled).

50. (Currently amended) ~~The composition of claim 49~~ A composition for the removal of etch residues from integrated circuits using copper materials, which consists essentially of:

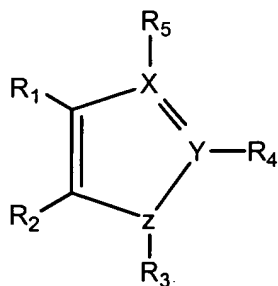
a choline compound;

water;

an organic solvent selected from the group consisting of dimethyl sulfoxide, dimethyl acetamide, ethylene glycol, ethylene glycol alkyl ether, diethylene glycol alkyl ether, triethylene glycol alkyl ether, propylene glycol, propylene glycol alkyl ether, N-methyl pyrrolidone, ethylene diamine, ethylene triamine, monoethanolamine, and diglycolamine; and

from about 0.5% by weight to about 5% by weight of a corrosion inhibitor selected from the group consisting of :

compounds of the general class

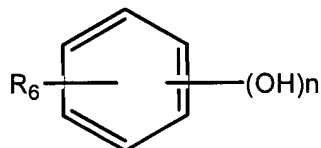


where X, Y, and Z, are chosen from C, N, O, S, and P; and

where pendant R groups R₁-R₅ are chosen from H, a substituted C₁-C₆ straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, hydroxyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, and sulfonic acid group;

salts of said compounds of the general class;

hydroxybenzene compounds of the general class



where $n = 1-4$, and

where R_6 is present from 2 to 5 times and is chosen from H, a substituted C_1-C_6 straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, sulfonic acid group; and

salts of said hydroxybenzene compounds,

wherein X is carbon and Y is nitrogen or X is nitrogen and Y is carbon, Z is nitrogen, and R_1-R_5 are hydrogen.

51. (Currently amended) ~~The composition of claim 49~~ A composition for the removal of etch residues from integrated circuits using copper materials, which consists essentially of:

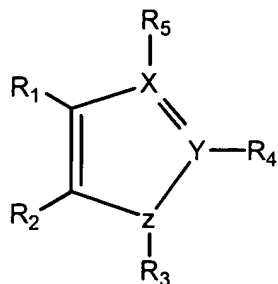
a choline compound;

water;

an organic solvent selected from the group consisting of dimethyl sulfoxide, dimethyl acetamide, ethylene glycol, ethylene glycol alkyl ether, diethylene glycol alkyl ether, triethylene glycol alkyl ether, propylene glycol, propylene glycol alkyl ether, N-methyl pyrrolidone, ethylene diamine, ethylene triamine, monoethanolamine, and diglycolamine; and

from about 0.5% by weight to about 5% by weight of a corrosion inhibitor selected from the group consisting of :

compounds of the general class

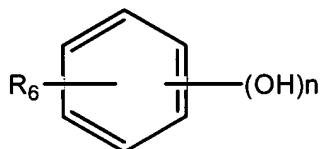


where X, Y, and Z, are chosen from C, N, O, S, and P; and

where pendant R groups R₁-R₅ are chosen from H, a substituted C₁-C₆ straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, hydroxyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, and sulfonic acid group;

salts of said compounds of the general class;

hydroxybenzene compounds of the general class



where n= 1-4, and

where R₆ is present from 2 to 5 times and is chosen from H, a substituted C₁-C₆ straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, sulfonic acid group; and

salts of said hydroxybenzene compounds,

wherein X is carbon and Y is nitrogen or X is nitrogen and Y is carbon, Z is nitrogen, R₃ is hydrogen, and R₄ and R₅ constitute a benzene ring.

52-60. (Canceled)

61. (Currently amended) ~~The composition of claim 60~~ A composition for the removal of etch residues from integrated circuits using copper materials and low k dielectric materials consisting essentially of:

a choline compound;

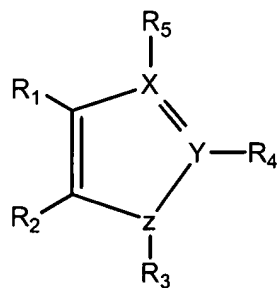
water;

from about 2 to about 12% by weight of hydroxylamine or hydroxylamine salt;

an organic solvent selected from the group consisting of dimethyl sulfoxide, dimethyl acetamide, ethylene glycol, ethylene glycol alkyl ether, diethylene glycol alkyl ether, triethylene glycol alkyl ether, propylene glycol, propylene glycol alkyl ether, N-methyl pyrrolidone, ethylene diamine, ethylene triamine, monoethanolamine, and diglycolamine; and

from about 0.5% by weight to about 5% by weight of a corrosion inhibitor selected from the group consisting of :

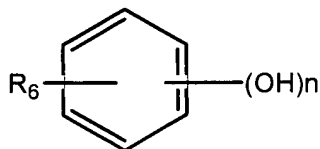
compounds of the general class



where X, Y, and Z, are chosen from C, N, O, S, and P; and

where pendant R groups R₁-R₅ are chosen from H, a substituted C₁-C₆ straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl

group, amidyl group, hydroxyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, and sulfonic acid group;
salts of said compounds of the general class;
hydroxybenzene compounds of the general class



where n= 1-4, and

where R₆ is present from 2 to 5 times and is chosen from H, a substituted C₁-C₆ straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, sulfonic acid group; and

salts of said hydroxybenzene compounds,

wherein X is carbon and Y is nitrogen or X is nitrogen and Y is carbon, Z is nitrogen, and R₁-R₅ are hydrogen.

62. (Currently amended) The composition of claim 60 A composition for the removal of etch residues from integrated circuits using copper materials and low k dielectric materials consisting essentially of:

a choline compound;

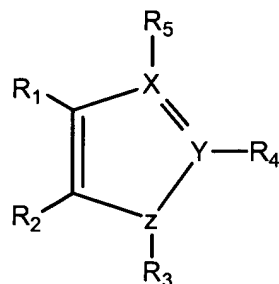
water;

from about 2 to about 12% by weight of hydroxylamine or hydroxylamine salt;

an organic solvent selected from the group consisting of dimethyl sulfoxide, dimethyl acetamide, ethylene glycol, ethylene glycol alkyl ether, diethylene glycol alkyl ether, triethylene glycol alkyl ether, propylene glycol, propylene glycol alkyl ether, N-methyl pyrrolidone, ethylene diamine, ethylene triamine, monoethanolamine, and diglycolamine; and

from about 0.5% by weight to about 5% by weight of a corrosion inhibitor selected from the group consisting of :

compounds of the general class

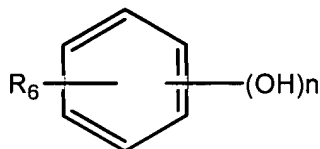


where X, Y, and Z, are chosen from C, N, O, S, and P; and

where pendant R groups R₁-R₅ are chosen from H, a substituted C₁-C₆ straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, hydroxyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, and sulfonic acid group;

salts of said compounds of the general class;

hydroxybenzene compounds of the general class



where n= 1-4, and

where R₆ is present from 2 to 5 times and is chosen from H, a substituted C₁-C₆ straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, sulfonic acid group; and

salts of said hydroxybenzene compounds,

wherein X is carbon and Y is nitrogen or X is nitrogen and Y is carbon, Z is nitrogen, R₃ is hydrogen, and R₄ and R₅ constitute a benzene ring.

63-65. (Canceled).

66. (Currently amended) ~~The composition of claim 65~~ A composition for stripping photoresist from integrated circuits using copper materials and low k dielectric materials consisting essentially of:

a choline compound;

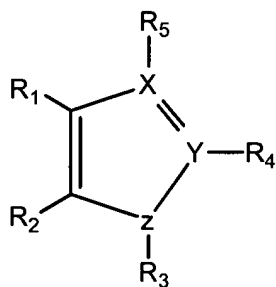
water;

from about 2 to about 12% by weight of hydroxylamine or hydroxylamine salt;

an organic solvent selected from the group consisting of dimethyl acetamide, dimethyl sulfoxide, propylene glycol, dipropylene glycol monomethyl ether, N-methyl pyrrolidone, and cyclohexyl pyrrolidone; and

from about 0.5% by weight to about 5% by weight of a corrosion inhibitor selected from the group consisting of :

compounds of the general class

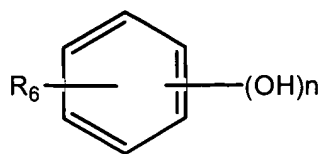


where X, Y, and Z, are chosen from C, N, O, S, and P; and

where pendant R groups R₁-R₅ are chosen from H, a substituted C₁-C₆ straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, hydroxyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, and sulfonic acid group;

salts of said compounds of the general class;

hydroxybenzene compounds of the general class



where $n = 1 - 4$, and

where R_6 is present from 2 to 5 times and is chosen from H, a substituted C_1-C_6 straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, sulfonic acid group; and salts of said hydroxybenzene compounds,

wherein X is carbon and Y is nitrogen or X is nitrogen and Y is carbon, Z is nitrogen, and R_1-R_5 are hydrogen.

67. (Currently amended) ~~The composition of claim 65~~ A composition for stripping photoresist from integrated circuits using copper materials and low k dielectric materials consisting essentially of:

a choline compound;

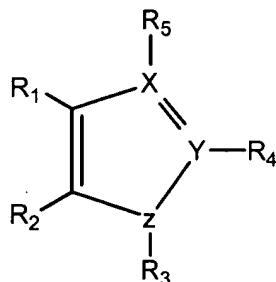
water;

from about 2 to about 12% by weight of hydroxylamine or hydroxylamine salt;

an organic solvent selected from the group consisting of dimethyl acetamide, dimethyl sulfoxide, propylene glycol, dipropylene glycol monomethyl ether, N-methyl pyrrolidone, and cyclohexyl pyrrolidone; and

from about 0.5% by weight to about 5% by weight of a corrosion inhibitor selected from the group consisting of:

compounds of the general class

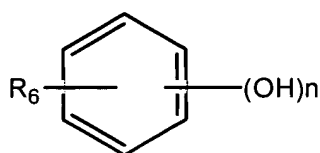


where X, Y, and Z, are chosen from C, N, O, S, and P; and

where pendant R groups R_1 - R_5 are chosen from H, a substituted C_1 - C_6 straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, hydroxyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, and sulfonic acid group;

salts of said compounds of the general class;

hydroxybenzene compounds of the general class



where $n = 1 - 4$, and

where R_6 is present from 2 to 5 times and is chosen from H, a substituted C_1 - C_6 straight, branched or cyclo alkyl, alkenyl or alkynyl group, straight or branched alkoxy group, a substituted acyl group, amidyl group, a halogen, carboxyl group, alkoxyalkyl group, alkylamino group, alkylsulfonyl group, sulfonic acid group; and
salts of said hydroxybenzene compounds,

wherein X is carbon and Y is nitrogen or X is nitrogen and Y is carbon, Z is nitrogen, R_3 is hydrogen, and R_4 and R_5 constitute a benzene ring.

68-73. (Canceled).